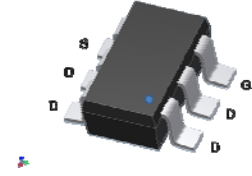
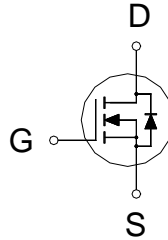


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV_{DSS}	30V
$R_{DS(on) (MAX.)}$	35m Ω
I_D	5.5A



Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_A = 25^\circ\text{C}$	I_D	5.5	A
	$T_A = 70^\circ\text{C}$		3.6	
Pulsed Drain Current ¹		I_{DM}	22	
Power Dissipation	$T_A = 25^\circ\text{C}$	P_D	1.25	W
	$T_A = 70^\circ\text{C}$		0.83	
Operating Junction & Storage Temperature Range		T_{j}, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Ambient	$R_{\theta JA}$		100	$^\circ\text{C} / \text{W}$

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$



ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$, Unless Otherwise Noted)

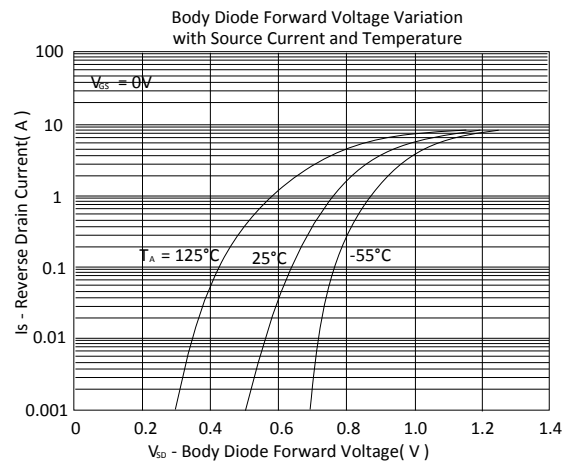
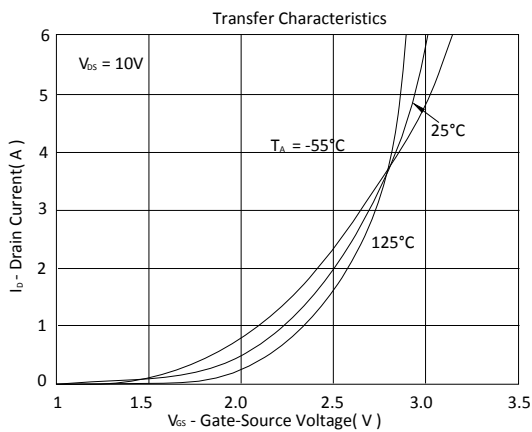
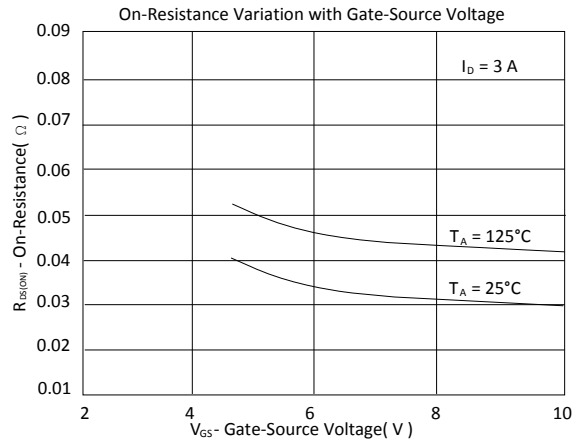
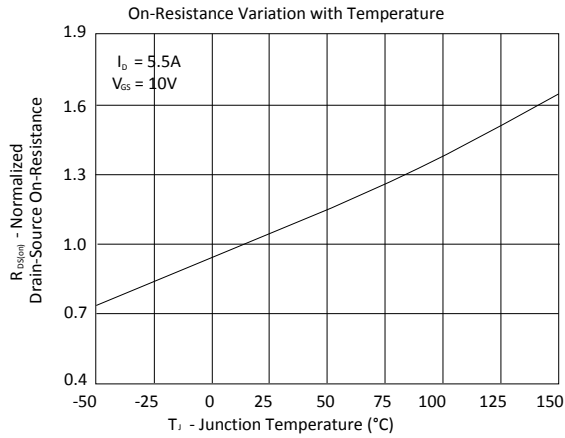
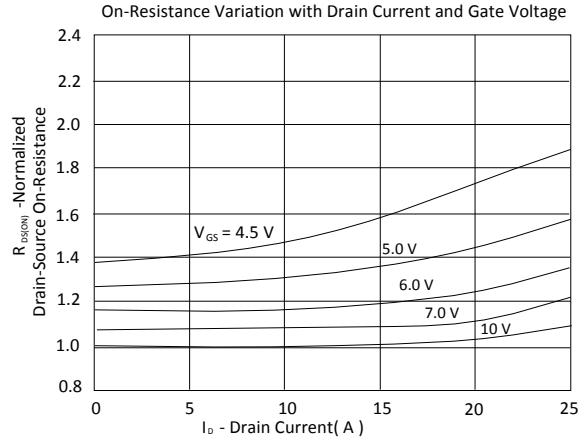
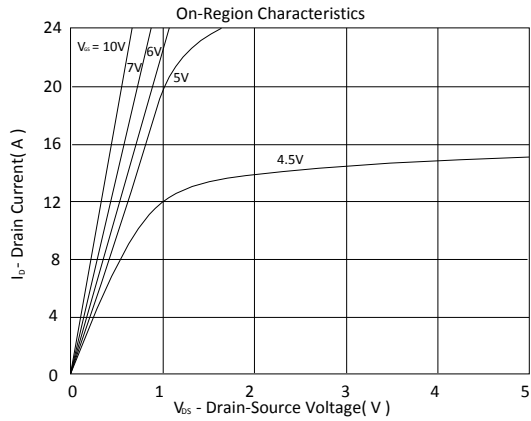
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	1.5	3.0	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$			1	μA
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 125\text{ }^\circ\text{C}$			10	
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = 5V, V_{GS} = 10V$	5.5			A
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 5.5A$		30	35	$m\Omega$
		$V_{GS} = 4.5V, I_D = 4.5A$		40	50	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 5.5A$		11		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 10V, f = 1MHz$		323		pF
Output Capacitance	C_{oss}			75		
Reverse Transfer Capacitance	C_{rss}			53		
Total Gate Charge ^{1,2}	Q_g	$V_{DS} = 10V, V_{GS} = 10V, I_D = 5.5A$		7.1		nC
Gate-Source Charge ^{1,2}	Q_{gs}			1.1		
Gate-Drain Charge ^{1,2}	Q_{gd}			2.2		
Turn-On Delay Time ^{1,2}	$t_{d(on)}$	$V_{DS} = 15V, I_D = 1A, V_{GS} = 10V, R_{GS} = 6\Omega$		8		nS
Rise Time ^{1,2}	t_r			12		
Turn-Off Delay Time ^{1,2}	$t_{d(off)}$			28		
Fall Time ^{1,2}	t_f			15		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_C = 25\text{ }^\circ\text{C}$)						
Continuous Current	I_S				2	A
Pulsed Current ³	I_{SM}				8	
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{GS} = 0V$			1.2	V

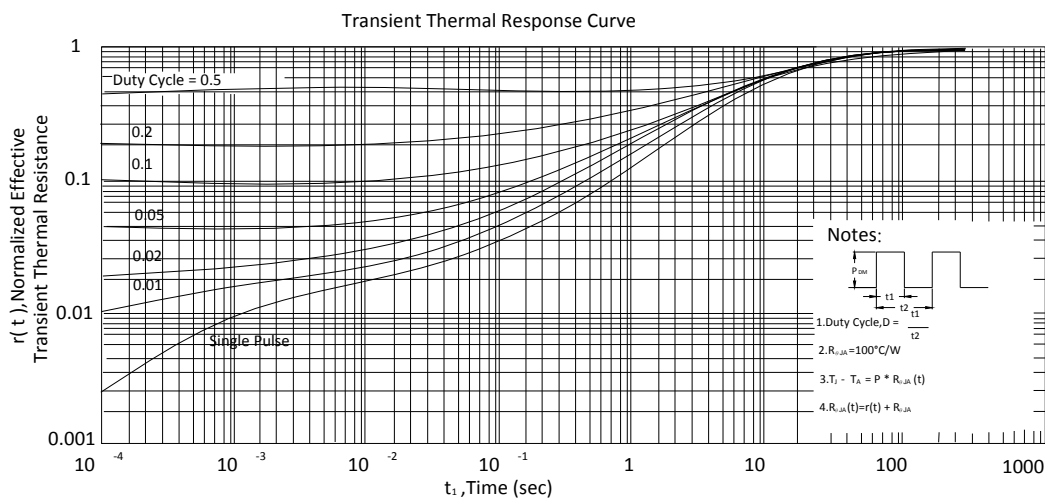
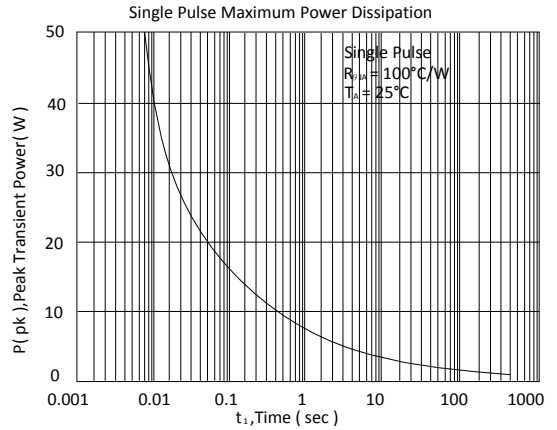
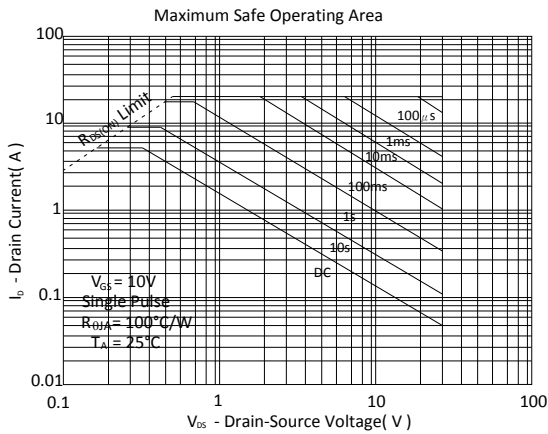
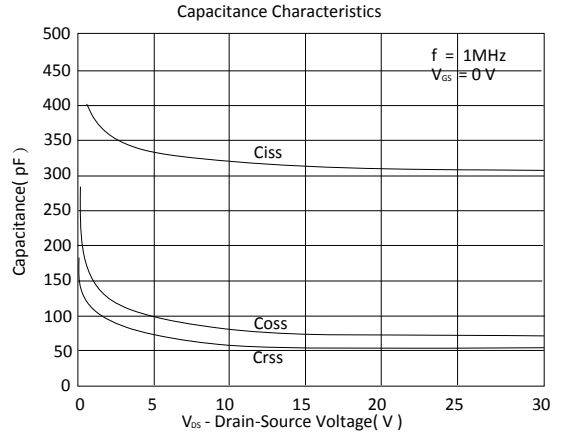
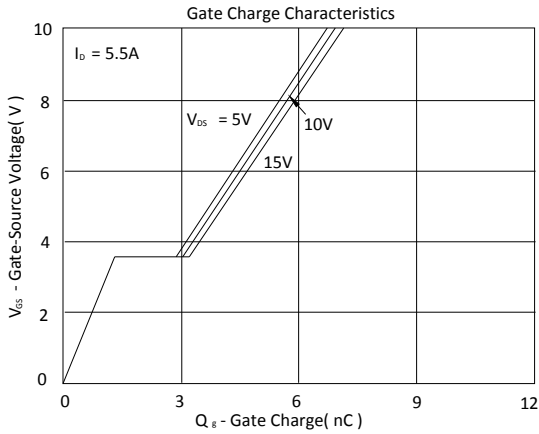
¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

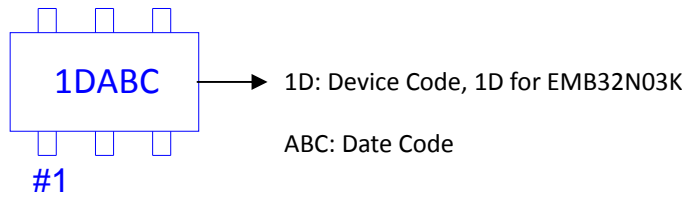
TYPICAL CHARACTERISTICS



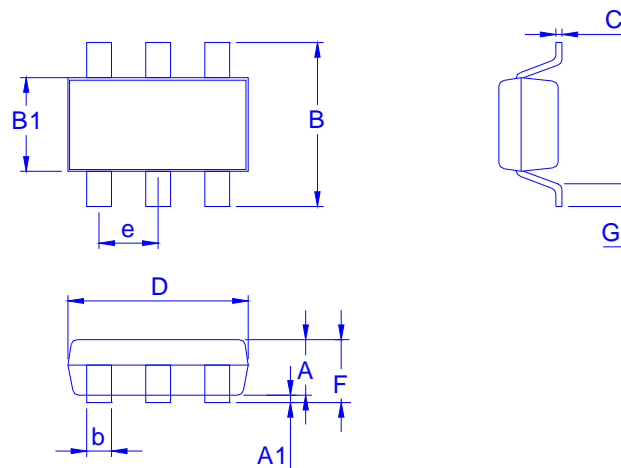


Ordering & Marking Information:

Device Name: EMB32N03K for TSOP-6



Outline Drawing



Dimension in mm

Dimension	A	A1	B	B1	b	C	D	e	F	G
Min.	0.85	0	2.50	1.50	0.30	0.08	2.70		0.85	0.20
Typ.	0.95		2.80	1.60	0.40		2.90	0.95		
Max.	1.25	0.15	3.10	1.70	0.50	0.20	3.10		1.40	0.60

Footprint

